

SOT821-1

plastic low profile fine-pitch ball grid array package; 228 balls; body 15 x 15 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA228
Package type industry code	LFPGA228
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-2-2004

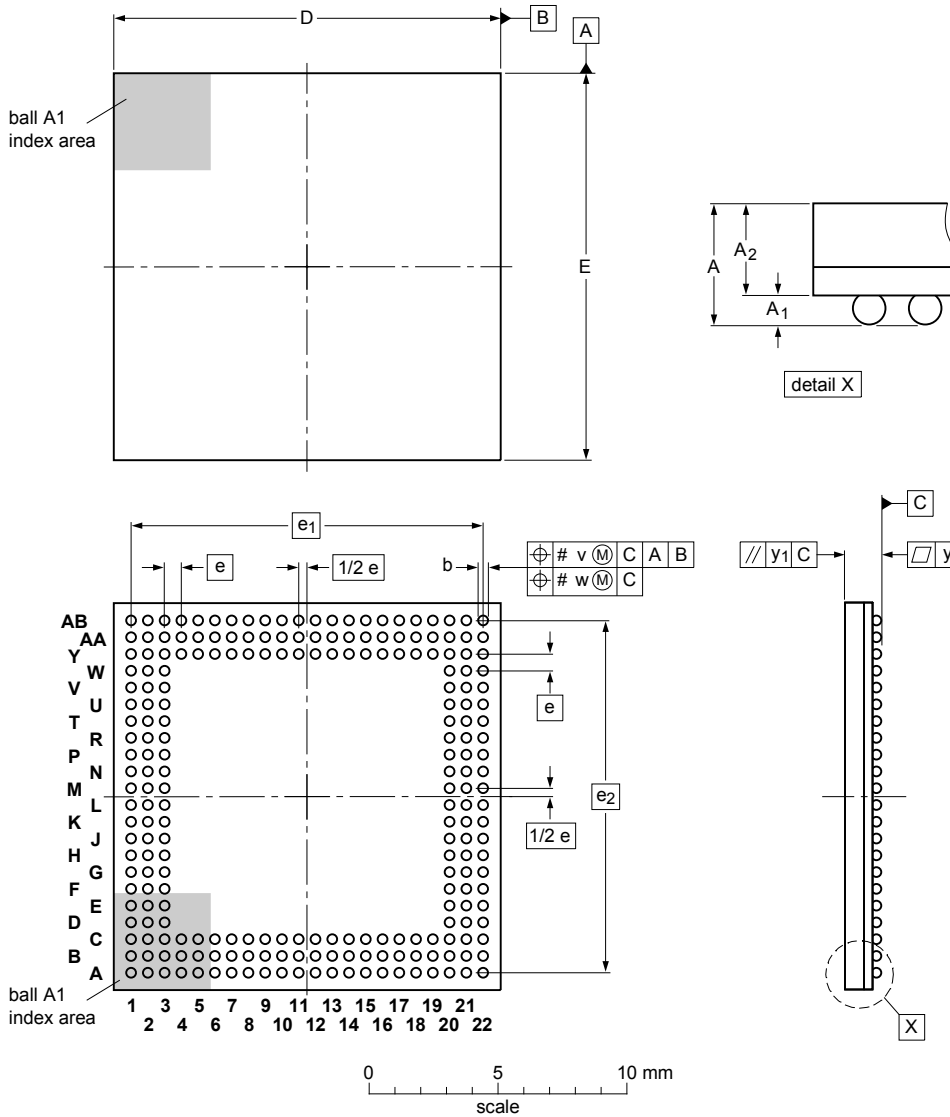
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.55	1.55	mm
A ₂	package height	0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination	-	-	228	-	



2. Package outline

LFBGA228: plastic low profile fine-pitch ball grid array package; 228 balls; body 15 x 15 x 1.05 mm SOT821-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.55	0.35 0.25	1.20 0.95	0.45 0.35	15.1 14.9	15.1 14.9	0.65	13.65	13.65	0.15	0.08	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT821-1	---	---	---			04-02-25

Fig. 1. Package outline LFBGA228 (SOT821-1)

3. Legal information

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